ePoP

Embedded Package-on-Package Memory for Wearables

Kingston's ePoP provides a highly integrated JEDEC standard component that combines Embedded MultiMedia Card (e•MMC) storage and Low-Power Double Data Rate (LPDDR) DRAM into a Package-on-Package (PoP) solution. ePoP is mounted directly on top of a compatible host System-on-a-Chip (SoC), which reduces Printed Circuit Board (PCB) space, and ensures optimum performance. ePoP is an ideal solution for space constrained applications such as wearables.

KEY BENEFITS

- By mounting directly on top of a host SoC, ePoP provides an ideal solution for small form factor applications such as wearables.
- Low-Power DRAM and optimized storage firmware reduces power consumption while delivering the high performance needed for battery powered wearable applications.
- Simplifies system design, reduces time to market, and shortens the qualification cycle.
- Multiple firmware configurations available to best fit your application requirements for performance, power, and life span.

MARKET SEGMENTS

IoT

Wearables

Augmented Reality (AR) / Virtual Reality (VR) devices

EPOP PART NUMBERS AND SPECIFICATIONS

LPDDR4x based ePoP

Part Number	Capacity		Description		Package	FBGA	Operating Temperature
	NAND (GB)	DRAM (Gb)	eMMC	DRAM	(mm)		
64EP16-M4MTB9W	64	16	5.1	LPDDR4x	8x9.5x0.6	144	-25°C ~ +85°C
64EP32-M4NTB9W	64	32	5.1	LPDDR4x	8x9.5x0.65	144	-25°C ~ +85°C

LPDDR5x based ePoP

Part Number	Capacity		Description		Package	FBGA	Operating Temperature
	NAND (GB)	DRAM (Gb)	eMMC	DRAM	(mm)		
64EP16-M5ATB9W	64	16	5.1	LPDDR5x	8x9.5x0.58	201	-25°C ~ +85°C
64EP32-M5BTB9G	64	32	5.1	LPDDR5x	8x9.5x0.65	201	-25°C ~ +85°C
64EP32-M5BTB9M	64	32	5.1	LPDDR5x	8x9.5x0.7	201	-25°C ~ +85°C